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Applicant: Adrian E. Ong  
Assignee: Inapac Technologies, Inc.  
Title: Layout And Use Of Bond Pads And Probe Pads For Testing Of Integrated Circuits Devices  
Application No.: 10/003,375 Filing Date: November 15, 2001  
Examiner: Unknown Group Art Unit: 2862  
Docket No.: M-9433 US Confirmation No.: 4697

San Francisco, California  
February 24, 2003

COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

**NOTICE OF CHANGE OF ADDRESS**

Dear Sir:

Please direct all correspondence in the above-identified application and with respect to any patent that issues on this application to the undersigned at this address:

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I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

2/24/03 Richard A. Pask  
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Respectfully submitted,

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